

MJ N-Channel Enhancement Mode Power MOSFET

Description

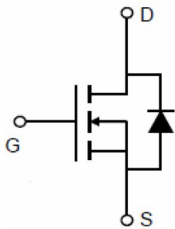
The MJ6045G uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

- ◆ $V_{DS}=60V, I_D=45A$
 $R_{DS(ON)}<13m\Omega$ @ $V_{GS}=10V$ (Typ:10m Ω)
 $R_{DS(ON)}<17m\Omega$ @ $V_{GS}=4.5V$ (Typ:13m Ω)
- ◆ High density cell design for ultra low R_{dson}
- ◆ Fully characterized avalanche voltage and current
- ◆ Low gate to drain charge to reduce switching losses

Application

- ◆ Power switching application
- ◆ Load switch



Schematic diagram



DFN5X6-8L top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJ6045G	MJ6045G	DFN5X6-8L	Ø330mm	12mm	5000

Absolute Maximum Ratings (Tc =25 °Cunless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	±20	V
Drain Current-Continuous	I_D	45	A
Drain Current-Continuous($T_c =100^{\circ}C$)	$I_{D(100^{\circ}C)}$	32	A
Pulsed Drain Current	I_{DM}	140	A
Single pulse avalanche energy ^(Note 5)	E_{AS}	260	mJ
Maximum Power Dissipation	P_D	60	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	$R_{\theta JC}$	2.08	°C/W
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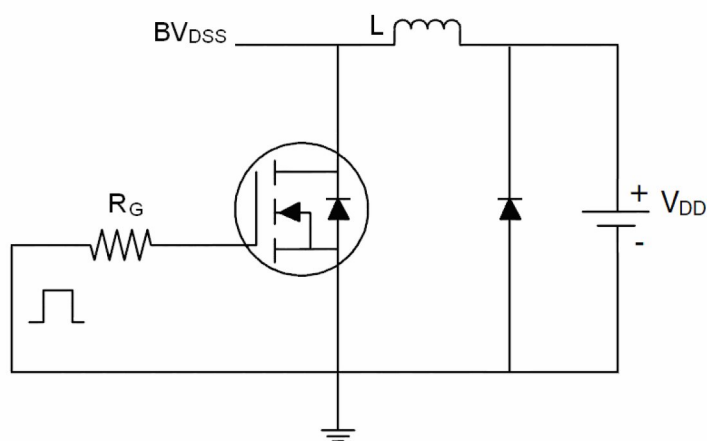
Electrical Characteristics (Tc =25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	60	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{DS} =±20V,V _{GS} =0V	-	-	±100	nA
On Characteristics ^(Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	1.2	1.8	2.2	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =20A	-	10	13	mΩ
		V _{GS} =4.5V, I _D =20A	-	13	17	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V,I _D =9A	25	-	-	S
Dynamic Characteristics ^(Note 4)						
Input Capacitance	C _{iss}	V _{DS} =30V,V _{GS} =0V, F=1.0MHz	-	2180	-	PF
Output Capacitance	C _{oss}		-	350	-	PF
Reverse Transfer Capacitance	C _{rss}		-	270	-	PF
Switching Characteristics ^(Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =30V,R _L =1Ω V _{GS} =10V,R _{Gen} =3Ω	-	8.5	-	nS
Turn-on Rise Time	t _r		-	6	-	nS
Turn-Off Delay Time	t _{d(off)}		-	30	-	nS
Turn-Off Fall Time	t _f		-	5	-	nS
Total Gate Charge	Q _g	V _{DS} =30V,I _D =20A, V _{GS} =10V	-	58	-	nC
Gate-Source Charge	Q _{gs}		-	8	-	nC
Gate-Drain Charge	Q _{gd}		-	17	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note 3)	V _{SD}	V _{GS} =0V,I _S =20A	-	-	1.2	V
Diode Forward Current ^(Note 2)	I _S		-	-	45	A
Reverse Recovery Time	t _{rr}	T _J =25°C, I _F =20A di/dt=100A/μs ^(Note 3)	-	30	-	nS
Reverse Recovery Charge	Q _{rr}		-	44	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible(turn-on is dominated by LS+LD)				

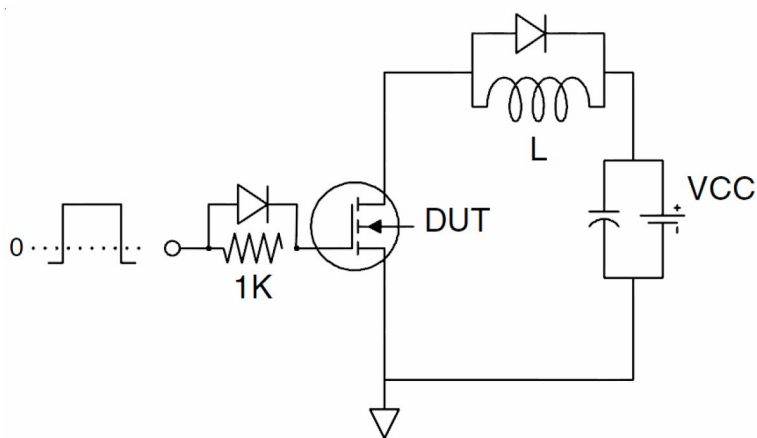
Notes:

- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Surface Mounted on FR4 Board, t≤10sec.
- ③ Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%.
- ④ Guaranteed by design, not subject to production
- ⑤ EAS condition：Tj=25℃,V_{DD}=30V,V_G=10V,L=0.5mH,Rg=25Ω

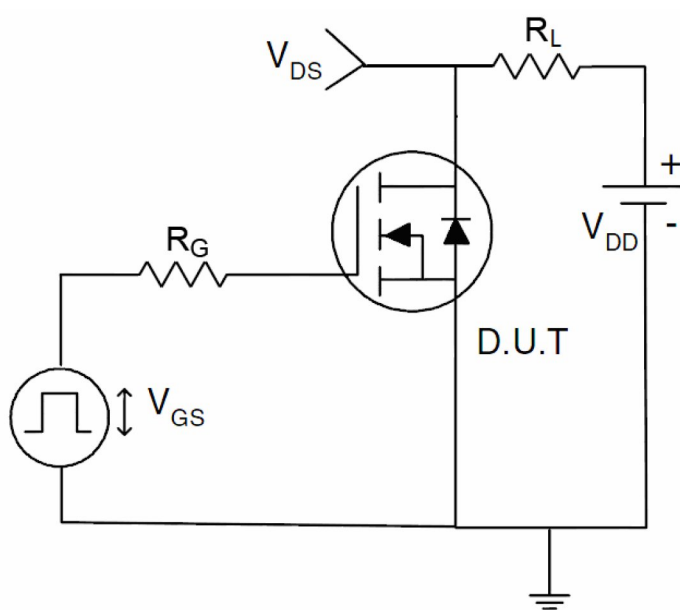
Test circuit



EAS test Circuit

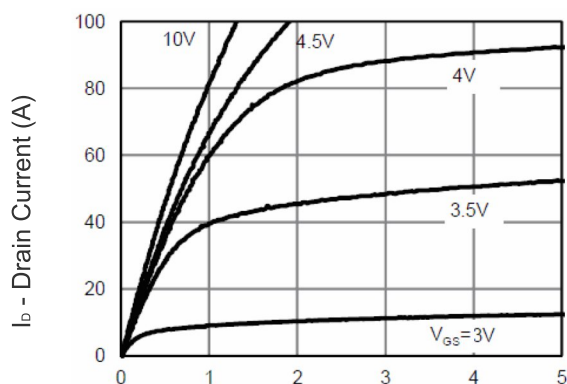


Gate charge test Circuit



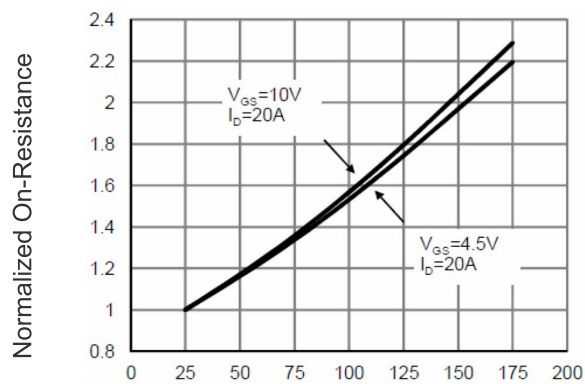
Switch Time Test Circuit

Typical Electrical and Thermal Characteristics (Curves)



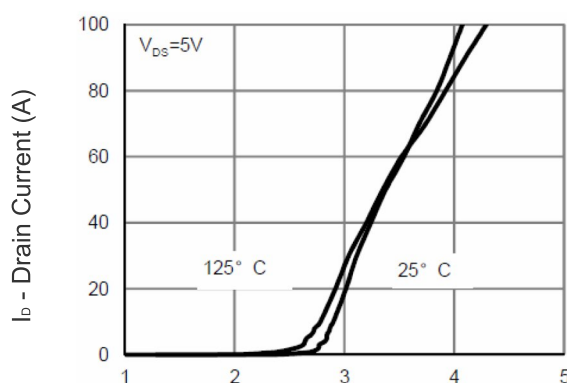
V_{ds} Drain-Source Voltage (V)

Figure 1 Output Characteristics



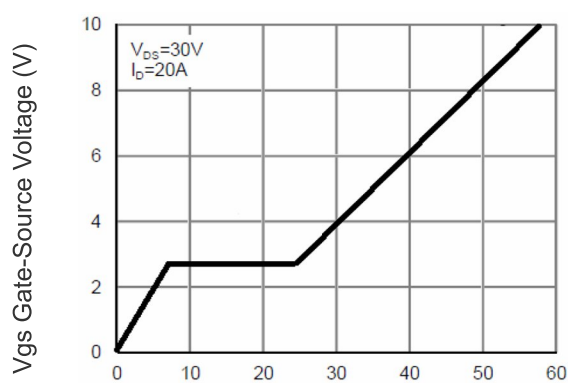
T_J -Junction Temperature(°C)

Figure 4 Rdson-Junction Temperature



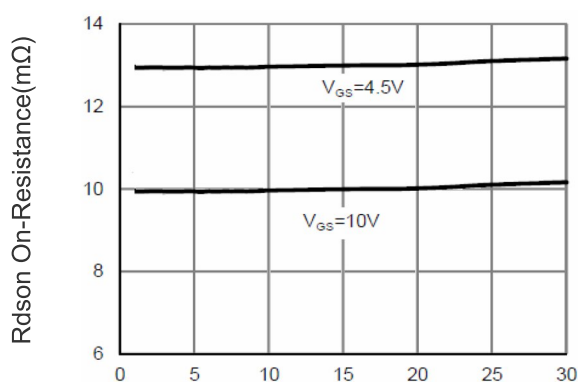
V_{gs} Gate-Source Voltage (V)

Figure 2 Transfer Characteristics



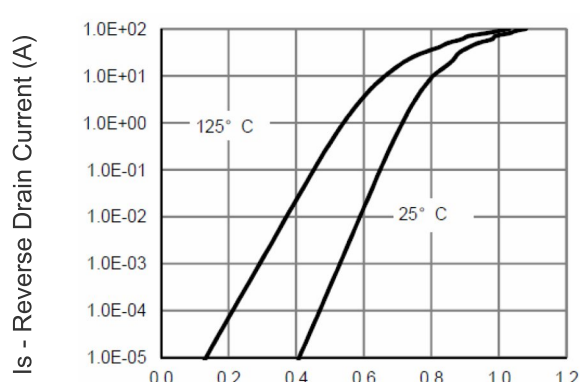
Q_g Gate Charge (nC)

Figure 5 Gate Charge



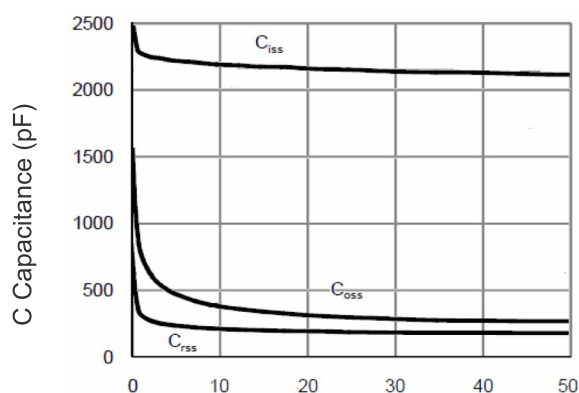
I_D - Drain Current (A)

Figure 3 Rdson- Drain Current

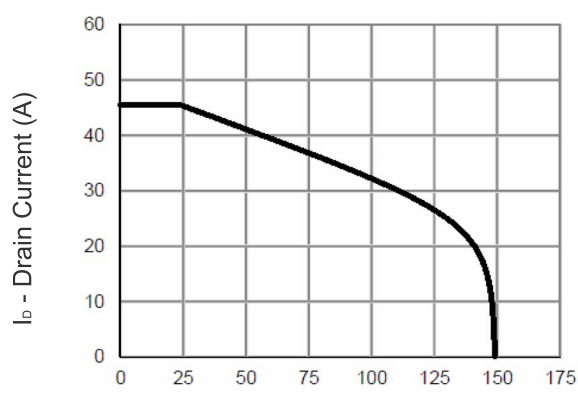


V_{sd} Source-Drain Voltage (V)

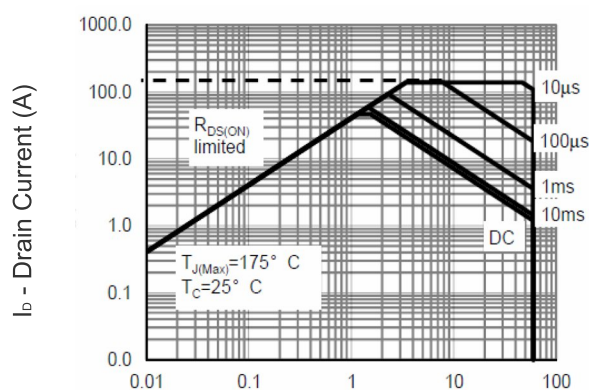
Figure 6 Source- Drain Diode Forward



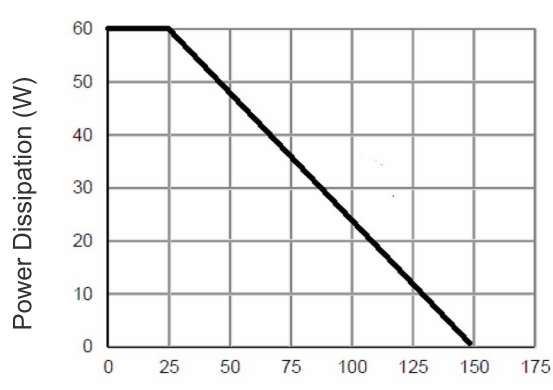
Vds Drain-Source Voltage (V)
Figure 7 Capacitance vs Vds



Tj -Junction Temperature(°C)
Figure 9 Current De-rating



Vds Drain-Source Voltage (V)
Figure 8 Safe Operation Area



Tj -Junction Temperature(°C)
Figure 10 Power De-rating

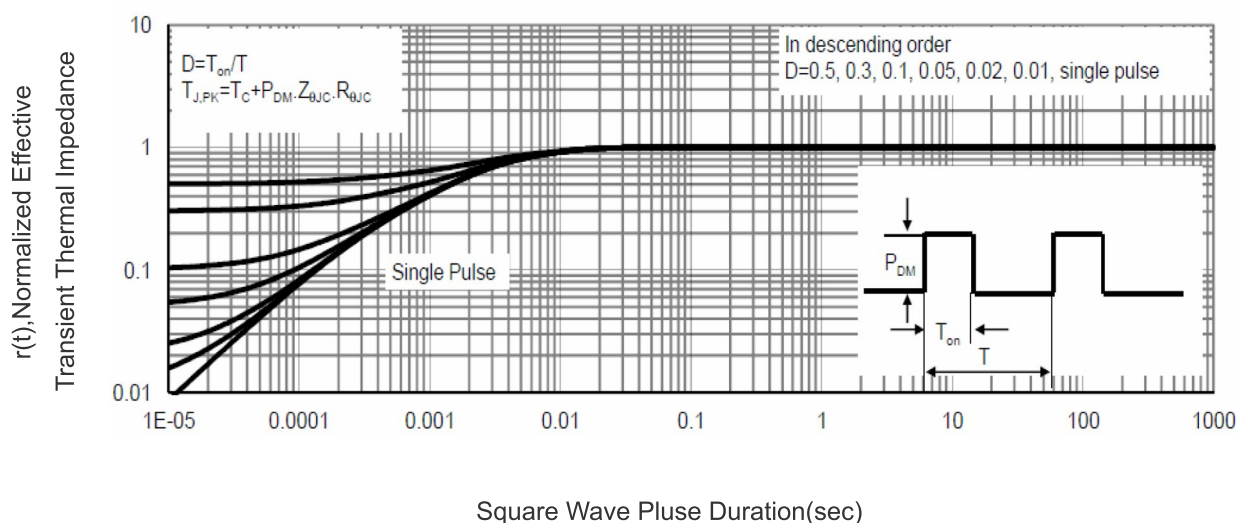
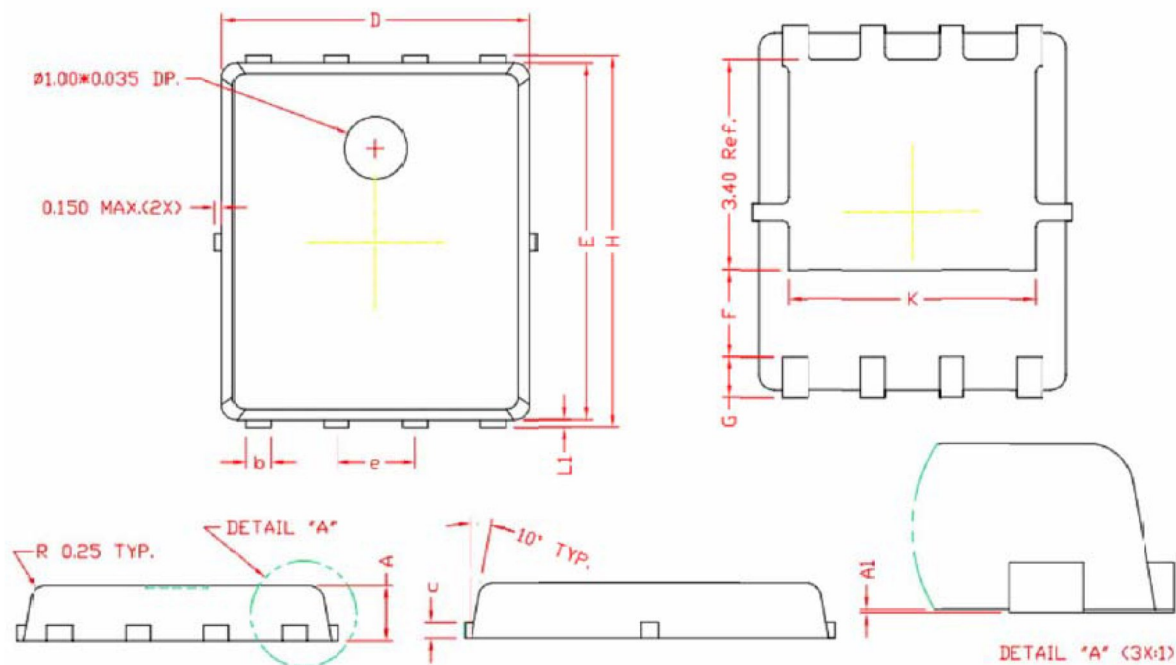


Figure 11 Normalized Maximum Transient Thermal Impedance

DFN5X6-8L Package Information



COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	0.80	0.90	1.00
A1	0.00	0.03	0.05
b	0.35	0.42	0.49
c	0.254 REF.		
D	4.90	5.00	5.10
F	1.40 REF.		
E	5.70	5.80	5.90
e	1.27 BSC.		
H	5.95	6.08	6.20
L1	0.10	0.14	0.18
G	0.60 REF.		
K	4.00 REF.		

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